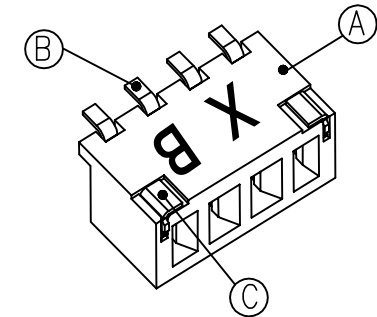
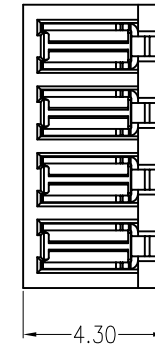
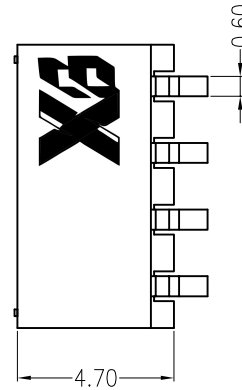
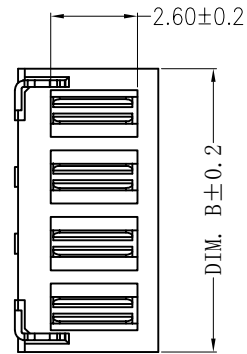
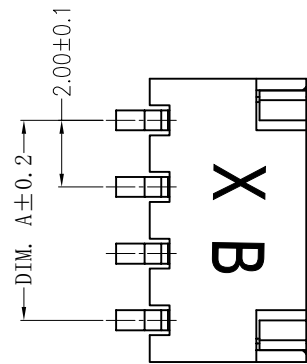


REV	ECN No.	DESCRIPTION	DESIGN	DATE
A0	—	Release	吴丹平	2017.10.26



Circuit	Dimensions (mm)		
	DIM. A	DIM. B	DIM. C
03	4.00	6.50	4.50
04	6.00	8.50	6.50

主要技术参数 Main Specifications

线 数 (Poles): 03 to 04

接触电阻 (Contact resistance): $\leq 30\text{m}\Omega$

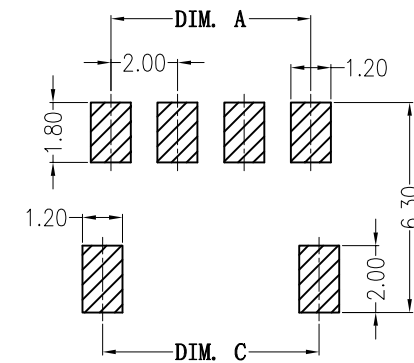
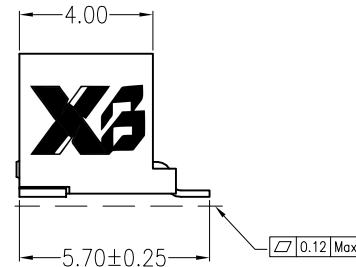
绝缘电阻 (Insulation resistance): $\geq 1000\text{M}\Omega$

额定电压 (Rated voltage): 275V AC DC

额定电流 (Rated current): 1.0A AC DC

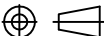
耐 电 压 (Withstand Voltage): 1000V AC/minute

温度范围 (Temperature Range): $-40^{\circ}\text{C} \sim +120^{\circ}\text{C}$



SUGGESTED PCB LAYOUT

XB-L2001AWR-**-***B1-*			
PART No.		PACKAGING:	
No.OF CIRCUITS:		R=REEL	
03~04		P=PE	
PLASTIC MATERIAL:		Metal code:	
F1K=LCP(BLACK)		1=PhosphorBronze	
F6M=LCP(BEIGE)		PLATING:	
		B=MATTE Sn	

C	CONTACT		2 PCS	PhosphorBronze	MATTE Sn-Tip
B	COVER		2~4 PCS	PhosphorBronze	MATTE Sn-Tip
A	HOUSING		1 PCS	LCP	UL 94V-0, COLOR:BLACK/BEIGE
ITEM	COMPONENT		Q'TY	MATERIAL	FINISH
 东莞市溪榜电子有限公司 DONG GUAN XI BANG ELECTRONICS CO., LTD TITLE: 2.0Pitch 90°wafer smt type					
.X±0.35		X.±	USE:		PART NO.:
.XX±0.25		.X±	CUSTOMER		L2001AWR-**-***B1-*
.XXX±0.15		.XX±	APPD: 邵敬和		DWG NO.:
--		--	CHKD: 田峰		
		UNITS: mm	DR: 蒋建银		SCALE 1 : 1
					SHEET 1 / 1